

JEDEC SOLID STATE
PRODUCT OUTLINE
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THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE

288 PIN DDR4 MINI DIMM,
0.50 MM PITCH

PACKAGE DESIGNATOR

DIM

NUMBER

MO-314

ISSUE

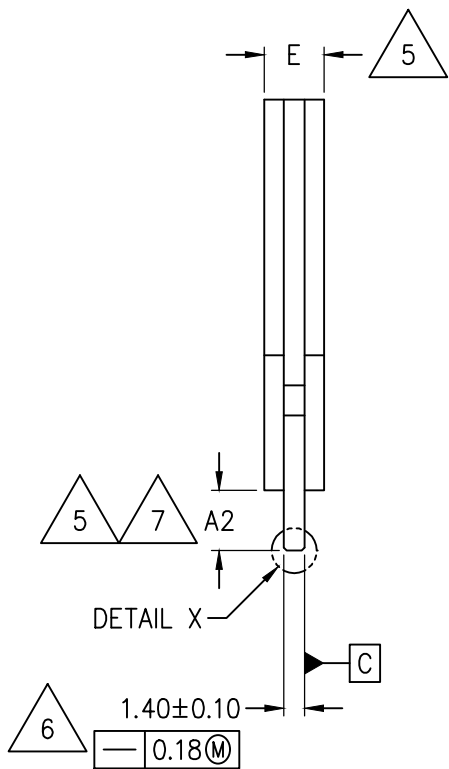
A.02

DATE

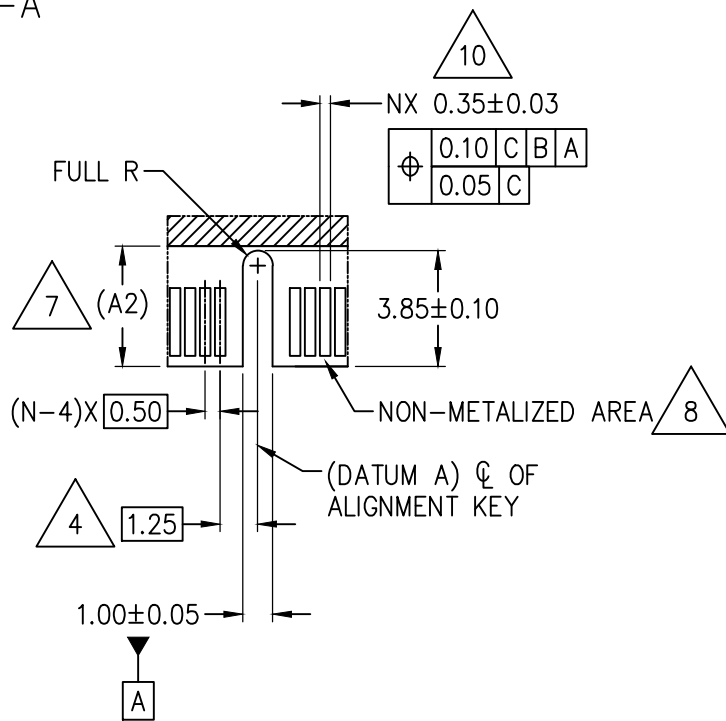
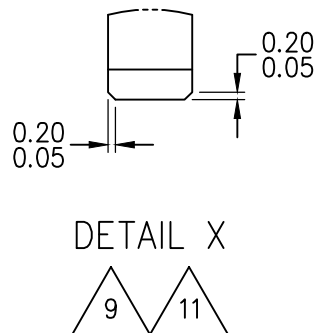
JUL 2016

SHEET

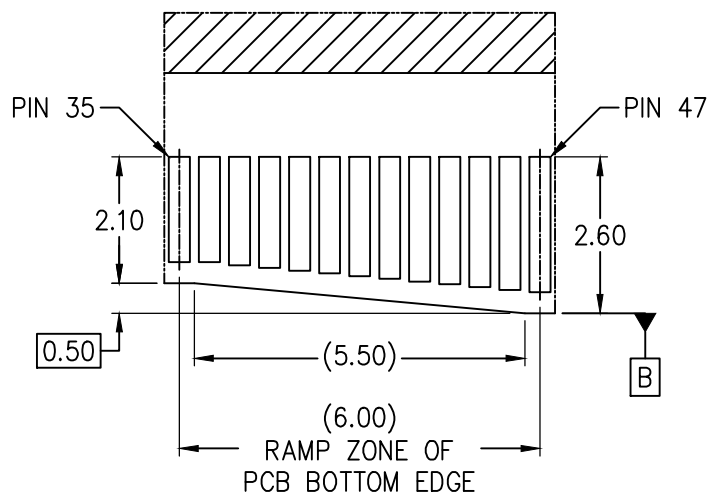
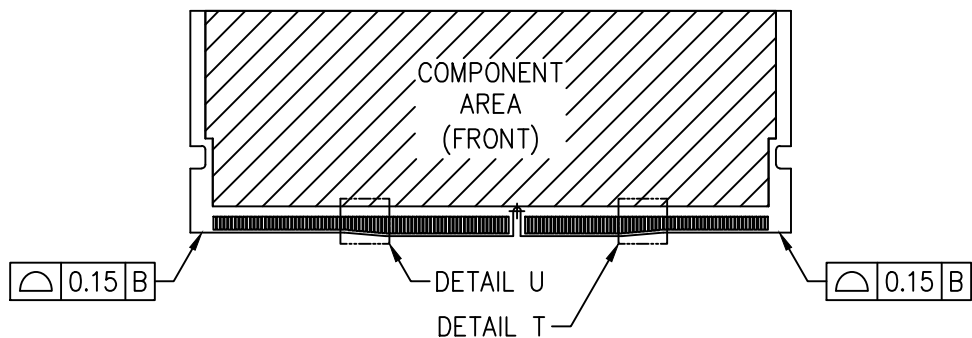
1 OF 6



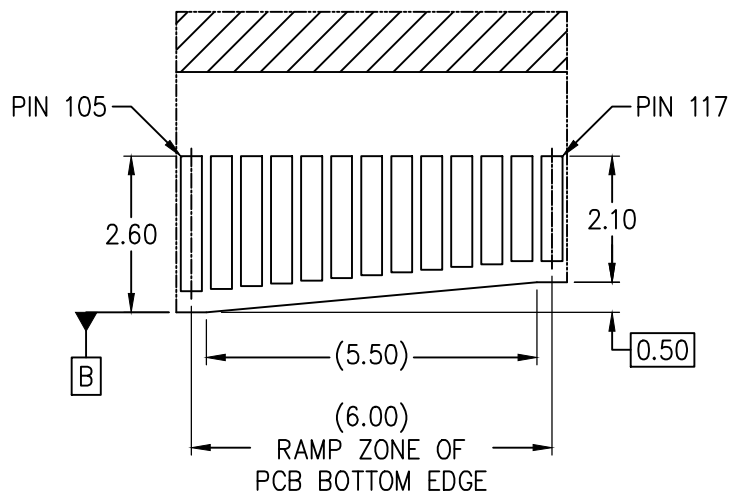
VIEW A-A



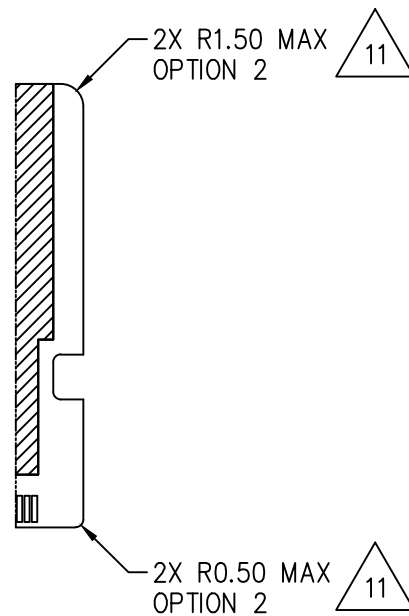
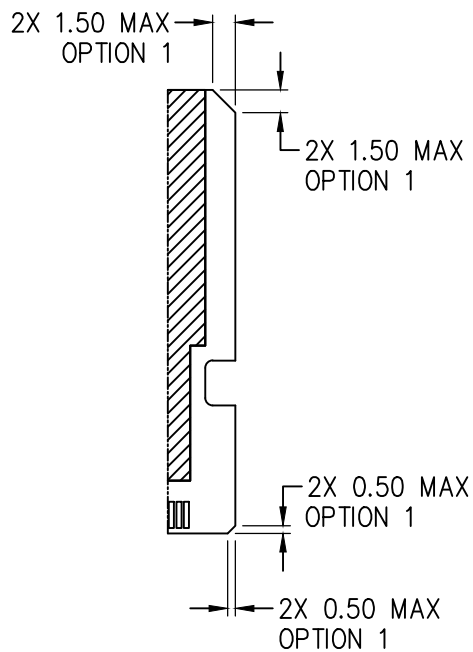
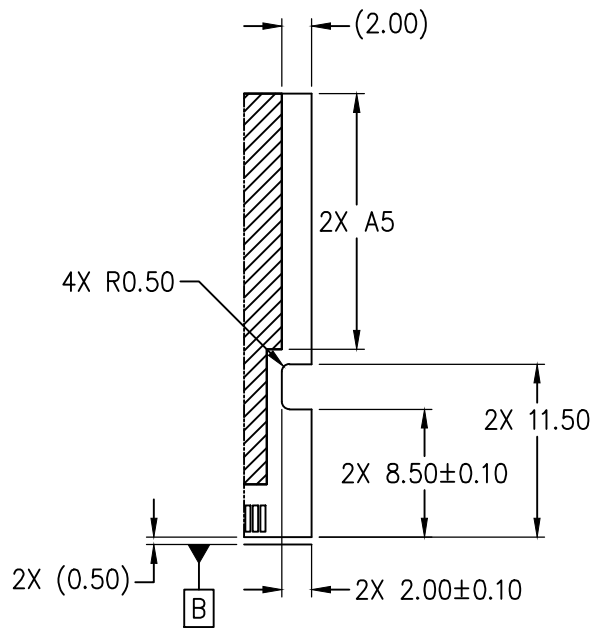
DETAIL Z



DETAIL U



DETAIL T



DETAIL W
ANY COMBINATION OF CHAMFERS OR RADII CAN BE USED

TABLE 1

COMMON DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A2	4.00	---	---	5, 7
D	79.85	80.00	80.15	
N	288			
NOTES	1, 2, 3			
REF	14-173			
ISSUE	A			

TABLE 2

VARIATIONS							
SYMBOL	AB			BB			
	MIN	NOM	MAX	MIN	NOM	MAX	NOTES
A	29.85	30.00	30.15	18.60	18.75	18.90	
A5	17.00	----	----	5.75	----	----	
E	----	----	4.00	----	----	4.00	5
NOTES	1, 2, 3						
REF	14–173						
ISSUE	A						

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5–2009.
2. TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
3. ALL DIMENSIONS ARE MM.



THE POSITION OF THE ALIGNMENT KEY DOES NOT DEFINE THE MODULE VOLTAGE.
THE JC-45 COMMITTEE CONTROLS THIS INFORMATION.
IT IS SHOWN HERE FOR REFERENCE ONLY, AND SUBJECT TO CHANGE.



DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDES.



CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING.
STRAIGHTNESS CALLOUT APPLIES TO ZONE DEFINED BY THE 4.00 MM CONTACT AREA
DIMENSION FOR THE ENTIRE LENGTH OF DIMENSION "D".



BORDER OF COMPONENT AREA.



EDGE OF CONTACT PADS AND TIE BARS, IF PRESENT, SHALL BE FREE OF BURRS.

APPLICATION NOTES:



THE BEVEL IS NOT TO HIT THE PLATED CONTACTS. THE BEVEL MUST BE APPLIED
ACROSS THE ENTIRE LENGTH OF THE MODULE AND BE FREE OF BURRS.



PLATING FOR CONTACT PADS ARE:

- 1) GOLD PLATING 0.76 MICROMETERS MINIMUM
OVER 2.00 MICROMETERS MINIMUM NICKEL.
- 2) GOLD PLATING 0.05 MICROMETERS MINIMUM
OVER 0.25 MICROMETERS MINIMUM PALLADIUM
OVER 2.00 MICROMETERS MINIMUM NICKEL.
- 3) GOLD PLATING 0.05 MICROMETERS MINIMUM
OVER 2.00 MICROMETERS MINIMUM NICKEL.

MODULE PLATING RECOMMENDATIONS TESTED PER INDUSTRY STANDARDS EIA 364–1000
RELIABILITY TESTING REQUIRES TEST MODULE, CONNECTOR, AND IDENTIFICATION OF
TEST CONDITIONS.



OPTIONAL CHAMFER OR RADIUS.

CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: JANUARY 2015	ITEM NUMBER: 14-173
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CHANGE RECORD HISTORY:

INITIAL ISSUE: A.01	DATE: MAY 2015	ITEM NUMBER: 14-173E
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LOCATION:	CHANGED FROM:	CHANGED TO:
SHEET 4		ADDED 4X R0.50

INITIAL ISSUE: A.02	DATE: JULY 2016	ITEM NUMBER: 14-183E
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LOCATION:	CHANGED FROM:	CHANGED TO:
SHEET 6, NOTE 6	...LENGTH OF 82.00MM.	...LENGTH OF DIMENSION "D".